

# AlSiC Hermetic Packaging

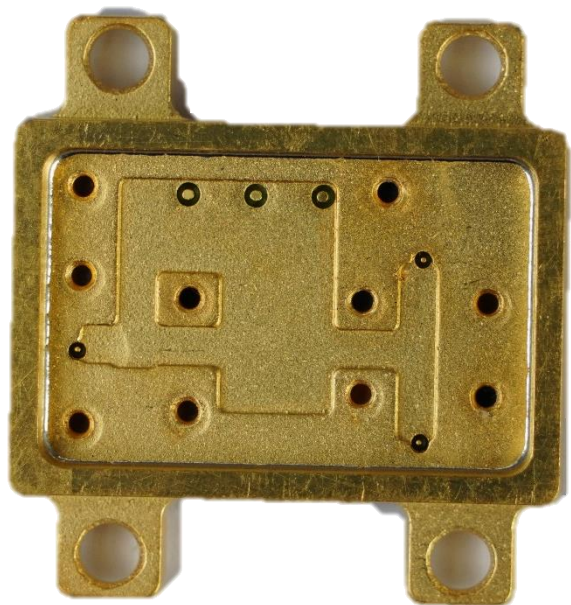
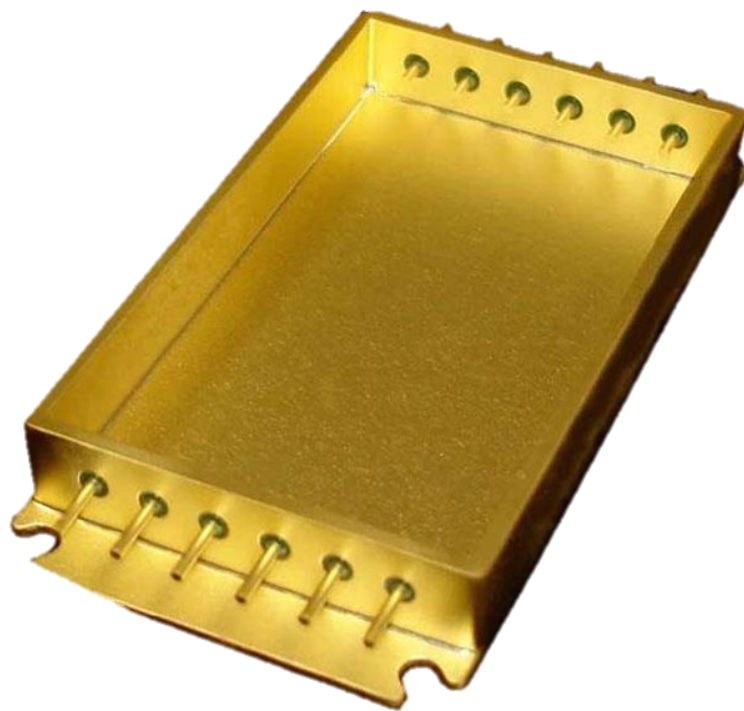


## AlSiC Hermetic Packaging Advantages

- 40-60% Lighter Weight Than CuMo and CuW
- Lower Cost Than CuMo and CuW
- Thermal Expansion Matching for Direct Attachment of GaAs and Substrates
- High Thermal Conductivity
  - AlSiC-9: 180 W/mK Minimum
- Readily Available Material
  - Standard and Non-Standard Base Thickness
  - Complex Shapes Without Machining

## Applications

- Military, Aerospace, and Communications
- Systems Subject to Shock and Vibration
- Weight Sensitive Applications



## Hermetic Seals

- Thermal Expansion Matched Seal
  - CPS Matched Seals are Produced by the "Two Step Sealing Process" for the Most Robust Hermetic Seal
- Brazed Ceramic Feedthrus for High Power Applications

